



Standoffs:

**QSS** 

02

(+)



(0.635 mm) .025"

# **HIGH-SPEED GROUND PLANE SOCKET**

# **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?QSS

Insulator Material: Liquid Crystal Polymer Contact Material: Phosphor Bronze

Plating: Au or Sn over 50 μ" (1.27 μm) Ni **Current Rating:** Contact: 1.8 A per pin (2 pins powered) Ground Plane: 23.1 A per ground plane (1 ground plane powered) Operating Temp: -55 °C to +125 °C Voltage Rating:

285 VĂC Max Cycles: **RoHS Compliant:** 

**PROCESSING** 

# Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (025-050) (0.15 mm) .006" max (075)\* (.004" sténcil solution may be available; contact IPG@samtec.com)

**Board Stacking:** 

For applications requiring more than two connectors per board contact ipg@samtec.com

## **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality



## ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
- 30 μ" (0.76 μm) Gold
- · Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount
- -LS2 Locking screw hole for QTS-RA-LS2

Some lengths, styles and options are non-standard, non-returnable.



POWER/SIGNAL APPLICATION



UMPT/UMPS for flexible two-piece power/signal solutions Integral metal plane for power or ground Polarized

HIGH-SPEED CHANNEL PERFORMANCE

**PLATING** 

**OPTION** 

### QSS/QTS @ 5 mm Mated Stack Height

Blade & Beam

01

(+)

(3.56)

140

Design

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

**OTHER OPTION** 

Alignment Pin

for mating

with QTS-RA

-K

= (8.25 mm) .325" DIA

Polyimide Film

Pick &

Place Pad

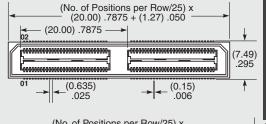
-TR

:Tape & Reel

-025, -050, -075 (50 total positions per bank)

NO. OF POSITIONS

**PER ROW** 



(No. of Positions per Row/25) x (20.00) .7875 + (10.90) .429000000000000000000 

DIA (No. of Positions per Row/25) x (20.00) .7875 + (5.72) .225 .285 (0.76).030 (0.89).035 (3.63).143

–GP **Guide Holes** 

= 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

= Gold Flash on Signal Pins and

Ground Plane, Matte Tin on tails

= Electro-Polished Selective  $50~\mu^{\text{\tiny H}}$  (1.27  $\mu m) min Au over$ 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

\*Note: -C Plating passes 10 year MFG testing

QTS LEAD STYLE	MATED HEIGHT WITH QSS
-01	(5.00) .197
-02	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances

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